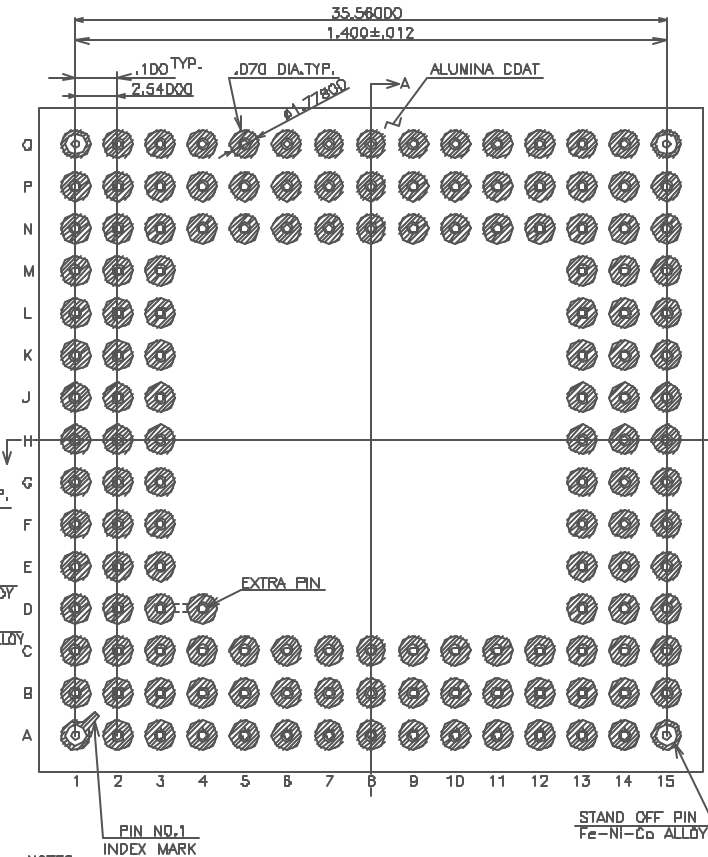
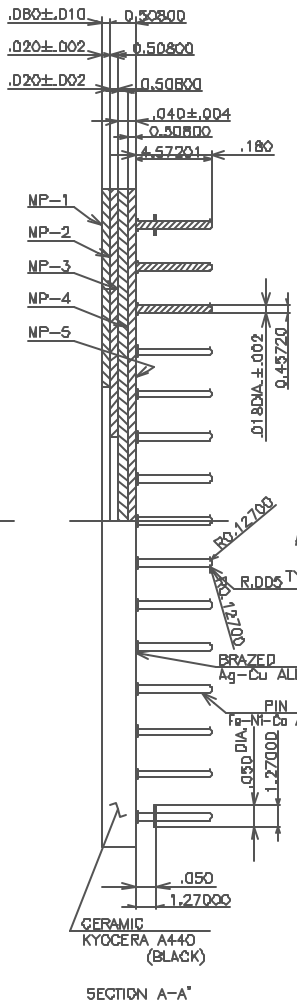
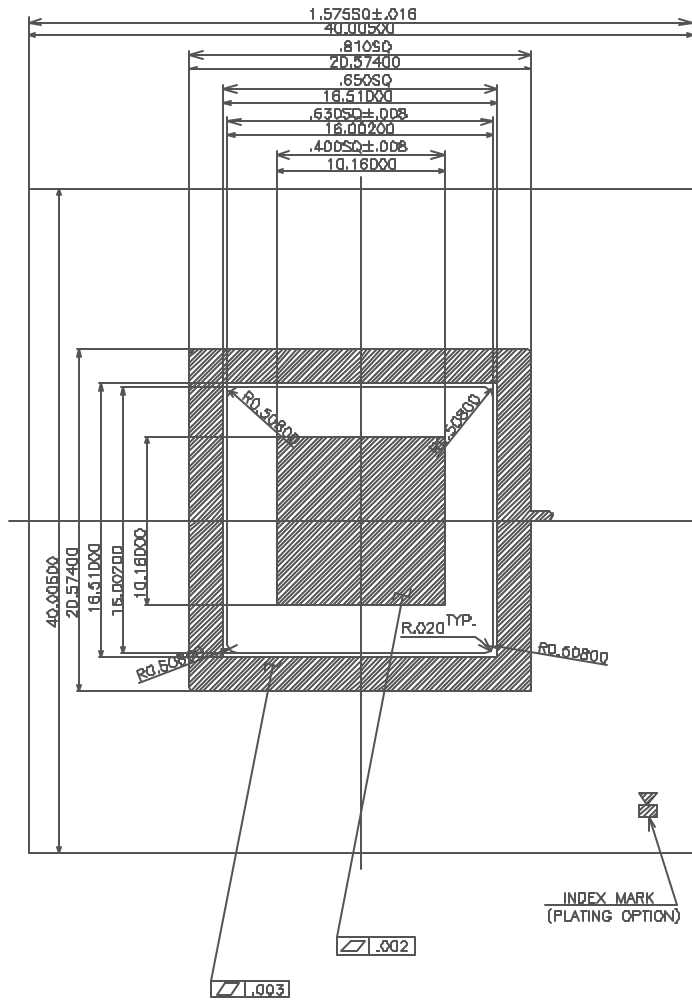


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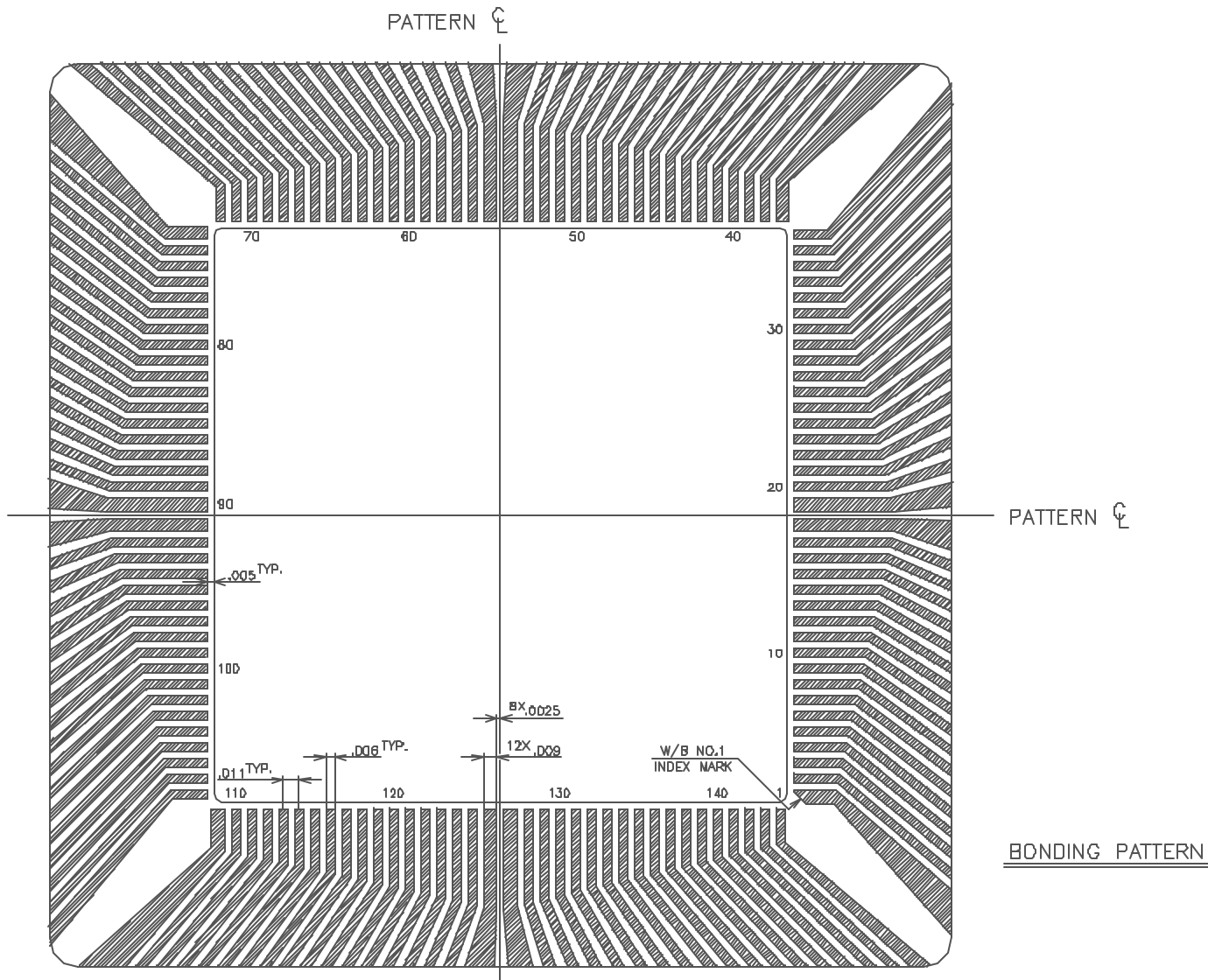


- NOTES :
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
 2. LEAD RESISTANCE :
 W/B NO. 18, 19, 54, 55, 90, 91, 126, 127 ----- 0.25 OHM MAX.
 W/B NO. 1, 37, 73, 109 ----- 0.3D OHM MAX.
 THE OTHERS ----- 0.90 OHM MAX.
 3. SEAL AREA TO BE METALLIZED.
 4. DIE ATTACH AREA TO BE METALLIZED.
 5. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.

MODIFICATION						NAME 144 PIN GRID ARRAY PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED ±1% N.L.T. ±.005 UNLESS OTHERWISE SPECIFIED	DRAWN K.Y.	CHECKED T.A.	APPROVED	DATE JUN 29 '85
	REDRAWN : CONVERTED CAD DATA. CHANGED	IN/WH DATE	TS/HK DRAWN	H/A/S/N CHECKED	H.S.A APPROVED	SCALE 5/1	MATERIAL AS INDICATED	DRAWING NO. KD-PB5032-A		SHEET 1/3	
						KYOCERA	KYOCERA CORPORATION KYOTO JAPAN	PB144R032-1 S=0 D=0			



SSM P/N CPG14440



MODIFICATION						NAME	144 PIN GRID ARRAY PACKAGE	TOLENANCE	UNLESS OTHERWISE SPECIFIED	DRAWN	CHECKED	APPROVED	DATE
						SCALE	2D / 1	MATERIAL		K.Y	T.A		JAN.29.75
	△ REDRAWN : CONVERTED CAD DATA.	INCLD	TS/HLK	HJA/SJM	H.SA								
	CHANGED	DATE	DRAWN	CHECKED	APPROVED		KYOCERA CORPORATION	KYOTO JAPAN	DRAWING NO.	KD-P85032-A		SHEET	2 / 3



